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2814

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

DONALD C. ABBOTT ET AL.

Serial No. 09/525,105 (TI-28098.1)

Filed: Herewith

For: SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING PLATED LEADFRAME  
INCLUDING GOLD SELECTIVELY COVERING AREAS TO BE SOLDERED

Art Unit 2814

Examiner Wael M. Fahmy

Customer No. 23494

Director of the United States  
Patent and Trademark Office  
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4-16-04

Jay M. Cantor, Reg. No. 19,906

**PRELIMINARY AMENDMENT**

Dear Sir:

Prior to the first Office action and responsive to the Notice of Non-Compliance dated March 25, 2004, please amend the above-identified application as follows: